

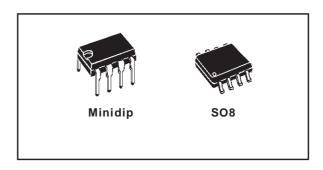
## UC2842B/3B/4B/5B UC3842B/3B/4B/5B

### HIGH PERFORMANCE CURRENT MODE PWM CONTROLLER

- TRIMMED OSCILLATOR FOR PRECISE FRE-QUENCY CONTROL
- OSCILLATOR FREQUENCY GUARANTEED AT 250kHz
- CURRENT MODE OPERATION TO 500kHz
- AUTOMATIC FEED FORWARD COMPENSA-TION
- LATCHING PWM FOR CYCLE-BY-CYCLE CURRENT LIMITING
- INTERNALLY TRIMMED REFERENCE WITH UNDERVOLTAGE LOCKOUT
- HIGH CURRENT TOTEM POLE OUTPUT
- UNDERVOLTAGE LOCKOUT WITH HYSTER-ESIS
- LOW START-UP AND OPERATING CURRENT



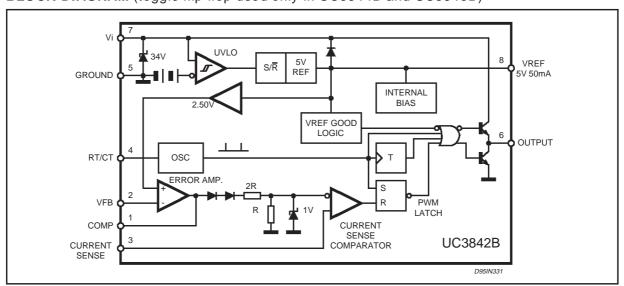
The UC384xB family of control ICs provides the necessary features to implement off-line or DC to DC fixed frequency current mode control schemes with a minimal external parts count. Internally implemented circuits include a trimmed oscillator for precise DUTY CYCLE CONTROL under voltage lock-outfeaturing start-up current less than 0.5mA, a precision reference trimmed for accuracy at the error amp input, logicto insure latched operation, a PWM



comparatorwhich also provides current limit control, and a totem pole output stage designed to source or sink high peak current. The output stage, suitable for driving N-Channel MOSFETs, is low in the offstate.

Differences between members of this family are the under-voltage lockout thresholds and maximum duty cycle ranges. The UC3842B and UC3844B have UVLO thresholds of 16V (on) and 10V (off), ideally suited off-line applications The corresponding thresholds for the UC3843B and UC3845B are 8.5 V and 7.9 V. The UC3842B and UC3843B can operate to duty cycles approaching 100%. A range of the zero to < 50 % is obtained by the UC3844B and UC3845B by the addition of an internal toggle flip flop which blanks the output off every other clock cycle.

#### BLOCK DIAGRAM (toggle flip flop used only in UC3844B and UC3845B)



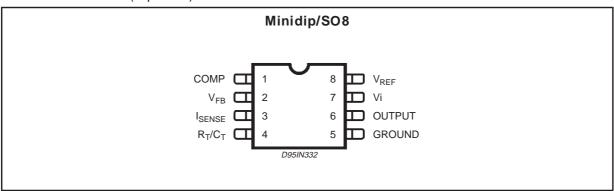
March 1999 1/15

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>i</sub>	Supply Voltage (low impedance source)	30	V
Vi	Supply Voltage (li < 30mA)	Self Limiting	
lo	Output Current	±1	А
Eo	Output Energy (capacitive load)	5	μJ
	Analog Inputs (pins 2, 3)	- 0.3 to 5.5	V
	Error Amplifier Output Sink Current	10	mA
P <sub>tot</sub>	Power Dissipation at T <sub>amb</sub> ≤ 25 °C (Minidip)	1.25	W
P <sub>tot</sub>	Power Dissipation at Tamb ≤ 25 °C (SO8)	800	mW
T <sub>stg</sub>	Storage Temperature Range	- 65 to 150	°C
TJ	Junction Operating Temperature	- 40 to 150	°C
TL	Lead Temperature (soldering 10s)	300	°C

<sup>\*</sup> All voltages are with respect to pin 5, all currents are positive into the specified terminal.

### PIN CONNECTION (top view)



#### **PIN FUNCTIONS**

No	Function	Description
1	COMP	This pin is the Error Amplifier output and is made available for loop compensation.
2	$V_{FB}$	This is the inverting input of the Error Amplifier. It is normally connected to the switching power supply output through a resistor divider.
3	I <sub>SENSE</sub>	A voltage proportional to inductor current is connected to this input. The PWM uses this information to terminate the output switch conduction.
4	R <sub>T</sub> /C <sub>T</sub>	The oscillator frequency and maximum Output duty cycle are programmed by connecting resistor $R_T$ to Vref and cpacitor $C_T$ to ground. Operation to 500kHz is possible.
5	GROUND	This pin is the combined control circuitry and power ground.
6	OUTPUT	This output directly drives the gate of a power MOSFET. Peak currents up to 1A are sourced and sunk by this pin.
7	V <sub>CC</sub>	This pin is the positive supply of the control IC.
8	$V_{ref}$	This is the reference output. It provides charging current for capacitor $C_T$ through resistor $R_T$ .

#### **ORDERING NUMBERS**

S08	Minidip
UC2842BD1; UC3842BD1	UC2842BN; UC3842BN
UC2843BD1; UC3843BD1	UC2843BN; UC3843BN
UC2844BD1; UC3844BD1	UC2844BN; UC3844BN
UC2845BD1; UC3845BD1	UC2845BN; UC3845BN

#### **THERMAL DATA**

Symbol	Description	Minidip	SO8	Unit
R <sub>th j-amb</sub>	Thermal Resistance Junction-ambient. max.	100	150	°C/W

**ELECTRICAL CHARACTERISTICS** ( [note 1] Unless otherwise stated, these specifications apply for  $-25 \le T_{amb} \le 85^{\circ}C$  for UC284XB;  $0 \le T_{amb} \le 70^{\circ}C$  for UC384XB;  $0 \le T_{amb} \le 70^{\circ}C$ 

Symbol	Parameter	Test Conditions	U	C284X	В	UC384XB			Unit
- I diameter		Test Conditions	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
REFERENC	CE SECTION								
$V_{REF}$	Output Voltage	$T_j = 25^{\circ}C$ $I_0 = 1mA$	4.95	5.00	5.05	4.90	5.00	5.10	V
$\Delta V_{REF}$	Line Regulation	$12V \leq V_i \leq 25V$		2	20		2	20	mV
$\Delta V_{REF}$	Load Regulation	$1 \leq I_0 \leq 20 mA$		3	25		3	25	mV
$\Delta V_{REF}/\Delta T$	Temperature Stability	(Note 2)		0.2			0.2		mV/°C
	Total Output Variation	Line, Load, Temperature	4.9		5.1	4.82		5.18	V
e <sub>N</sub>	Output Noise Voltage	$10$ Hz $\leq$ f $\leq$ $10$ KHz $T_j = 25$ °C (note 2)		50			50		μV
	Long Term Stability	$T_{amb} = 125^{\circ}C$ , 1000Hrs (note 2)		5	25		5	25	mV
I <sub>SC</sub>	Output Short Circuit		-30	-100	-180	-30	-100	-180	mA
OSCILLAT	OR SECTION								
f <sub>OSC</sub>	Frequency	$T_j = 25^{\circ}C$	49	52	55	49	52	55	KHz
		$T_A = T_{low}$ to $T_{high}$ $T_J = 25^{\circ}C (R_T = 6.2k, C_T = 1nF)$	48 225	250	56 275	48 225	250	56 275	KHz KHz
Δf <sub>OSC</sub> /ΔV	Frequency Change with Volt.	V <sub>CC</sub> = 12V to 25V	-	0.2	1	-	0.2	1	%
Δf <sub>OSC</sub> /ΔT	Frequency Change with Temp.	$T_A = T_{low}$ to $T_{high}$	-	1	-	-	0.5	-	%
Vosc	Oscillator Voltage Swing	(peak to peak)	-	1.6	-	-	1.6	-	V
I <sub>dischg</sub>	Discharge Current (V <sub>OSC</sub> =2V)	$T_J = 25^{\circ}C$ $T_A = T_{low}$ to $T_{high}$	7.8 7.5	8.3 –	8.8 8.8	7.8 7.6	8.3 –	8.8 8.8	mA mA
ERROR AN	MP SECTION					•		•	
V <sub>2</sub>	Input Voltage	V <sub>PIN1</sub> = 2.5V	2.45	2.50	2.55	2.42	2.50	2.58	V
I <sub>b</sub>	Input Bias Current	$V_{FB} = 5V$		-0.1	-1		-0.1	-2	μΑ
	A <sub>VOL</sub>	$2V \le V_0 \le 4V$	65	90		65	90		dB
BW	Unity Gain Bandwidth	T <sub>J</sub> = 25°C	0.7	1		0.7	1		MHz
PSRR	Power Supply Rejec. Ratio	$12V \le V_i \le 25V$	60	70		60	70		dB
Io	Output Sink Current	$V_{PIN2} = 2.7V  V_{PIN1} = 1.1V$	2	12		2	12		mA
lo	Output Source Current	VPIN2 = 2.3V VPIN1 = 5V	-0.5	-1		-0.5	-1		mA
	V <sub>OUT</sub> High	$V_{PIN2} = 2.3V;$ R <sub>L</sub> = 15K $\Omega$ to Ground	5	6.2		5	6.2		V
	V <sub>OUT</sub> Low	<del></del>		0.8	1.1		0.8	1.1	V
CURRENT	SENSE SECTION								
G <sub>V</sub>	Gain	(note 3 & 4)	2.85	3	3.15	2.85	3	3.15	V/V
V <sub>3</sub>	Maximum Input Signal	V <sub>PIN1</sub> = 5V (note 3)	0.9	1	1.1	0.9	1	1.1	V
SVR	Supply Voltage Rejection	$12 \leq V_i \leq 25V \text{ (note 3)}$		70			70		dB
I <sub>b</sub>	Input Bias Current			-2	-10		-2	-10	μΑ
	Delay to Output			150	300		150	300	ns

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#### UC2842B/3B/4B/5B - UC3842B/3B/4B/5B

#### **ELECTRICAL CHARACTERISTICS** (continued)

Symbol	Parameter	Test Conditions	UC284XB			UC384XB			Unit
Syllibol	Parameter	rest conditions	Min.	Тур.	Max.	Min.	Тур.	Max.	Onit
OUTPUT S	ECTION								
V <sub>OL</sub>	Output Low Level	I <sub>SINK</sub> = 20mA		0.1	0.4		0.1	0.4	V
		I <sub>SINK</sub> = 200mA		1.6	2.2		1.6	2.2	V
V <sub>OH</sub>	Output High Level	I <sub>SOURCE</sub> = 20mA	13	13.5		13	13.5		V
		I <sub>SOURCE</sub> = 200mA	12	13.5		12	13.5		V
V <sub>OLS</sub>	UVLO Saturation	VCC = 6V; I <sub>SINK</sub> = 1mA		0.1	1.1		0.1	1.1	V
t <sub>r</sub>	Rise Time	$T_j = 25^{\circ}C  C_L = 1nF  (2)$		50	150		50	150	ns
t <sub>f</sub>	Fall Time	$T_j = 25^{\circ}C  C_L = 1nF  (2)$		50	150		50	150	ns
UNDER-VO	LTAGE LOCKOUT SECTIO	N							
	Start Threshold	X842B/4B	15	16	17	14.5	16	17.5	V
		X843B/5B	7.8	8.4	9.0	7.8	8.4	9.0	V
	Min Operating Voltage	X842B/4B	9	10	11	8.5	10	11.5	V
	After Turn-on	X843B/5B	7.0	7.6	8.2	7.0	7.6	8.2	V
PWM SEC	TION								
	Maximum Duty Cycle	X842B/3B	94	96	100	94	96	100	%
		X844B/5B	47	48	50	47	48	50	%
	Minimum Duty Cycle				0			0	%
TOTAL ST	ANDBY CURRENT								
I <sub>st</sub> Start-up Current		$V_i = 6.5V$ for UCX843B/45B		0.3	0.5		0.3	0.5	mA
		$V_i = 14V$ for UCX842B/44B		0.3	0.5		0.3	0.5	mA
l <sub>i</sub>	Operating Supply Current	$V_{PIN2} = V_{PIN3} = 0V$		12	17		12	17	mA
V <sub>iz</sub>	Zener Voltage	$I_i = 25\text{mA}$	30	36		30	36		V

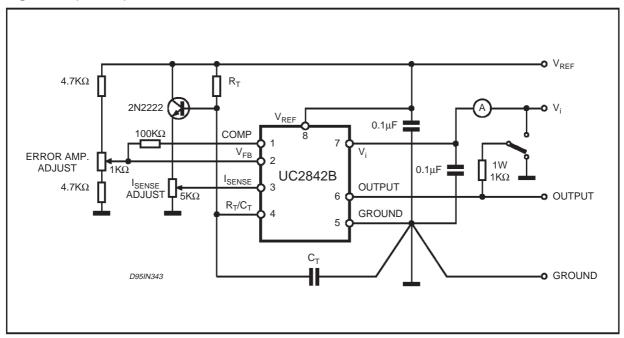
Notes: 1. Max package power dissipation limits must be respected; low duty cycle pulse techniques are used during test maintain T<sub>j</sub> as close to T<sub>amb</sub> as possible.
 These parameters, although guaranteed, are not 100% tested in production.
 Parameter measured at trip point of latch with V<sub>PIN2</sub> = 0.

$$A = \frac{\Delta V_{PIN1}}{\Delta V_{PIN3}} ; 0 \le V_{PIN3} \le 0.8 V$$

<sup>4.</sup> Gain defined as:

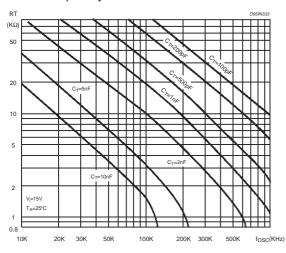
<sup>5.</sup> Adjust V<sub>i</sub> above the start threshold before setting at 15 V.

Figure 1: Open Loop Test Circuit.

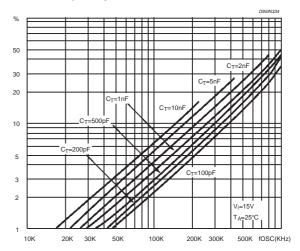


High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and  $5 \, \text{K}\Omega$  potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

**Figure 2:** Timing Resistor vs. Oscillator Frequency

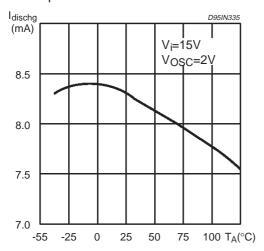


**Figure 3:** Output Dead-Time vs. Oscillator Frequency

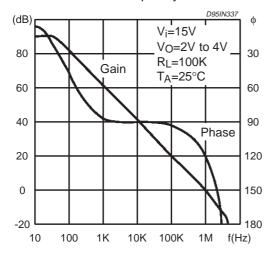


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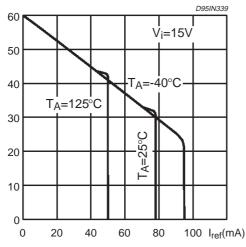
**Figure 4:** Oscillator Discharge Current vs. Temperature.



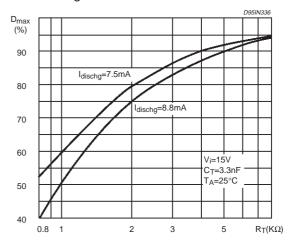
**Figure 6:** Error Amp Open-Loop Gain and Phase vs. Frequency.



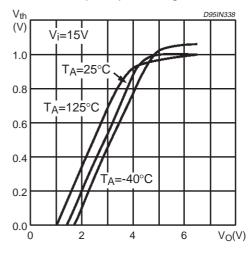
**Figure 8:** Reference Voltage Change vs. Source Current.



**Figure 5:** Maximum Output Duty Cycle vs. Timing Resistor.



**Figure 7:** Current Sense Input Threshold vs. Error Amp Output Voltage.



**Figure 9:** Reference Short Circuit Current vs. Temperature.

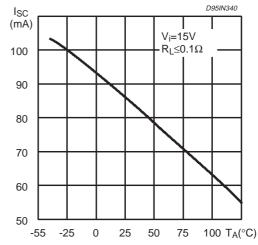


Figure 11: Supply Current vs. Supply Voltage.

Figure 10: Output Saturation Voltagevs. Load Current.

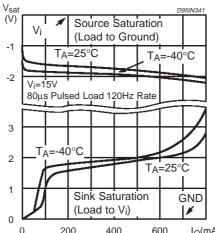
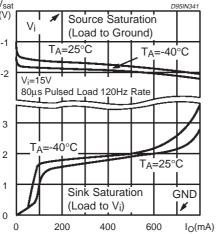


Figure 12: Output Waveform.



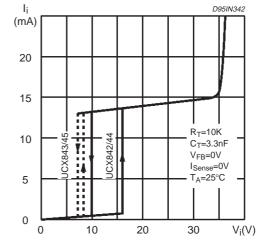


Figure 13: Output Cross Conduction

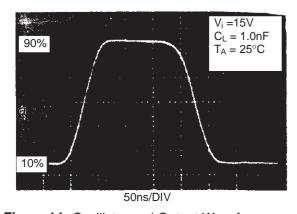
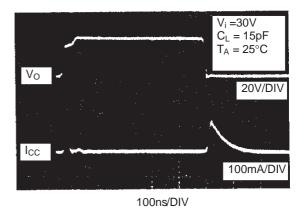
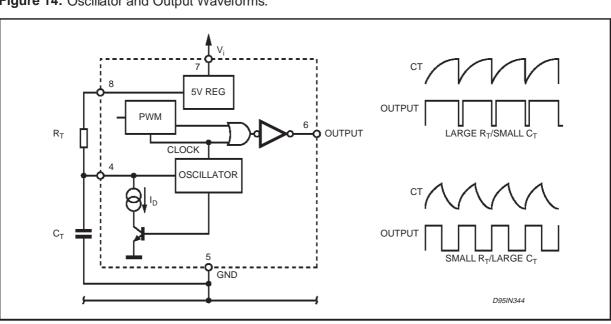


Figure 14: Oscillator and Output Waveforms.



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Figure 15: Error Amp Configuration.

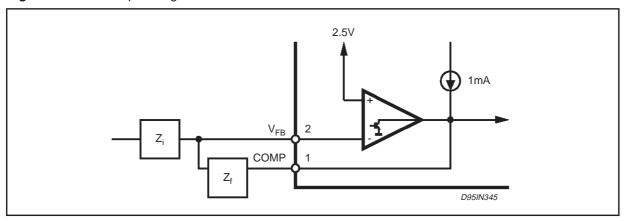


Figure 16: Under Voltage Lockout.

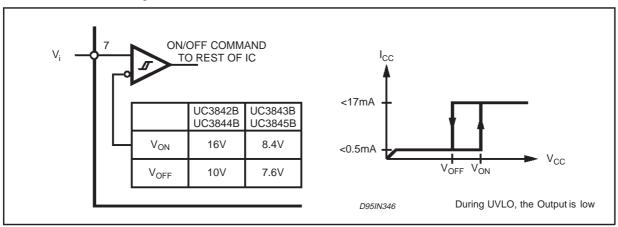
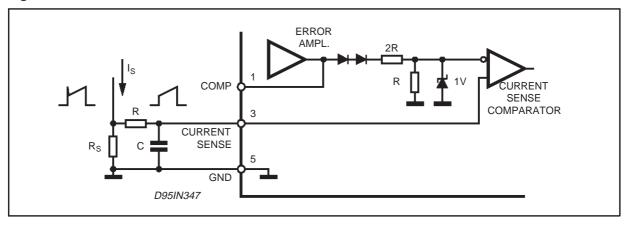


Figure 17: Current Sense Circuit.



Peak current (is) is determined by the formula

$$I_{S \text{ max}} \approx \frac{1.0 \text{ V}}{\text{Rs}}$$

A small RC filter may be required to suppress switch transients.

Figure 18: Slope Compensation Techniques.

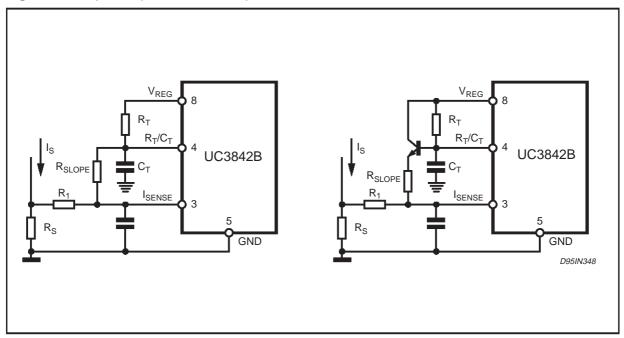


Figure 19: Isolated MOSFET Drive and Current Transformer Sensing.

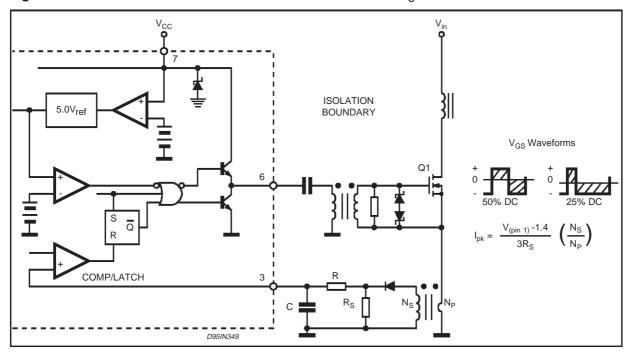


Figure 20: Latched Shutdown.

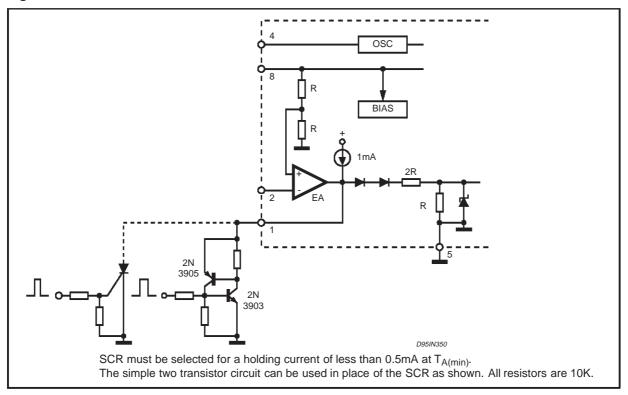


Figure 21: Error Amplifier Compensation

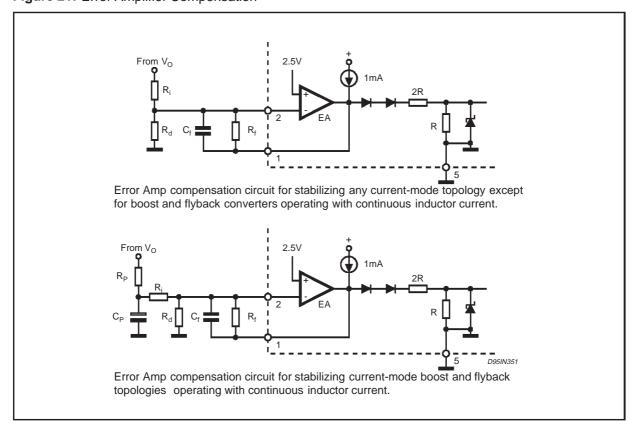


Figure 22: External Clock Synchronization.

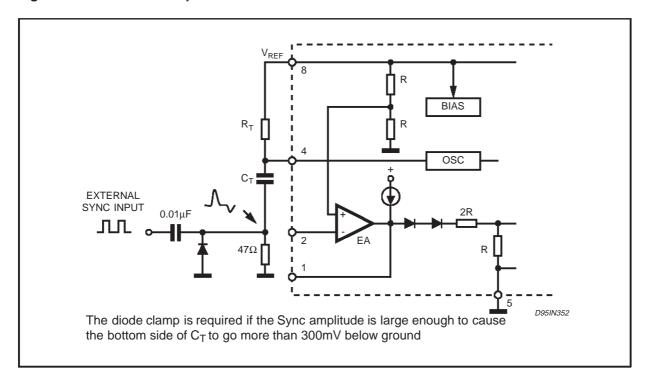


Figure 23: External Duty Cycle Clamp and Multi Unit Synchronization.

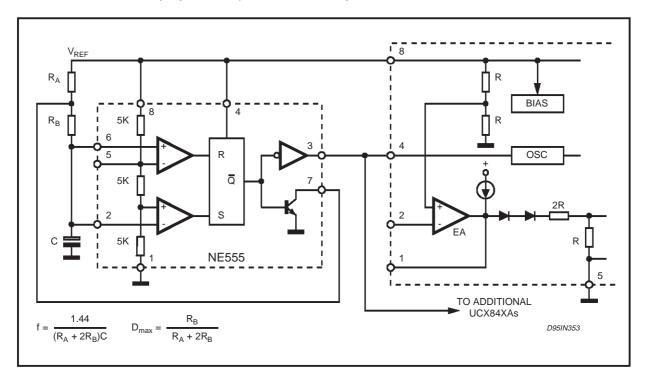


Figure 24: Soft-Start Circuit

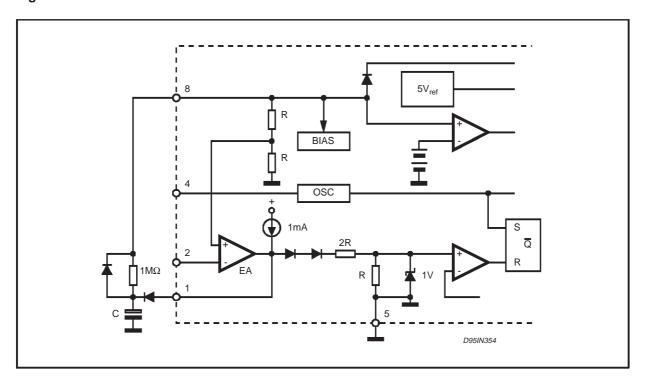
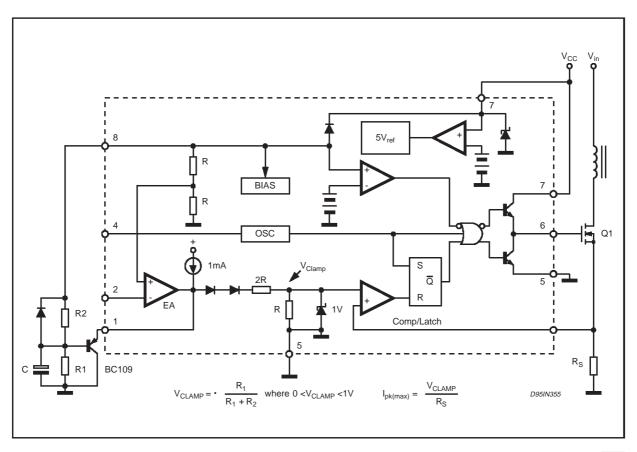
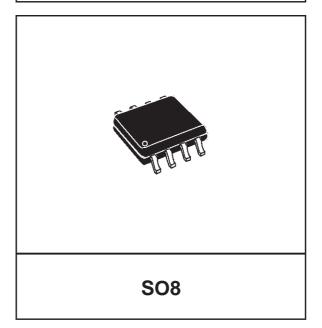


Figure 25: Soft-Start and Error Amplifier Output Duty Cycle Clamp.

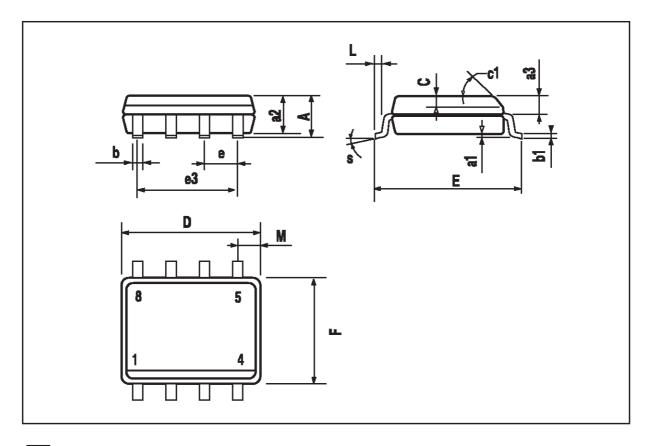


DIM.	mm			inch					
Dilvi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.			
Α			1.75			0.069			
a1	0.1		0.25	0.004		0.010			
a2			1.65			0.065			
a3	0.65		0.85	0.026		0.033			
b	0.35		0.48	0.014		0.019			
b1	0.19		0.25	0.007		0.010			
С	0.25		0.5	0.010		0.020			
c1			45° (	(typ.)					
D (1)	4.8		5.0	0.189		0.197			
Е	5.8		6.2	0.228		0.244			
е		1.27			0.050				
еЗ		3.81			0.150				
F (1)	3.8		4.0	0.15		0.157			
L	0.4		1.27	0.016		0.050			
М			0.6			0.024			
S	8° (max.)								

# OUTLINE AND MECHANICAL DATA

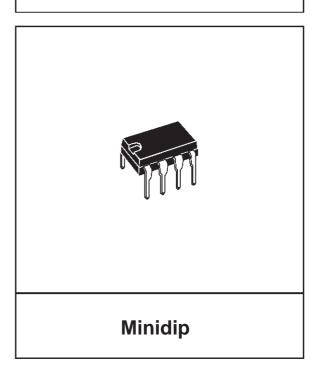


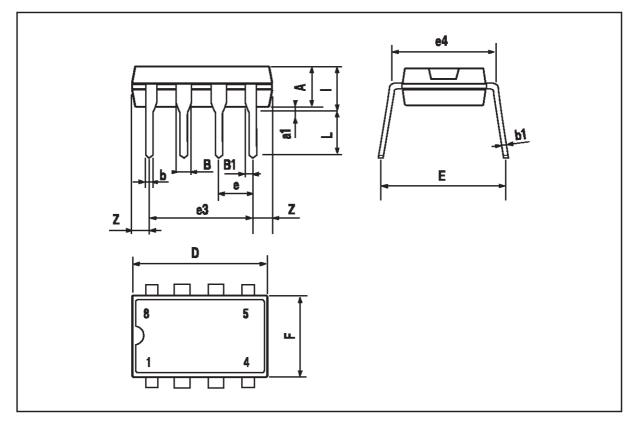
<sup>(1)</sup> D and F do not include mold flash or protrusions. Mold flash or potrusions shall not exceed 0.15mm (.006inch).



DIM.	mm			inch			
Dim.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А		3.32			0.131		
a1	0.51			0.020			
В	1.15		1.65	0.045		0.065	
b	0.356		0.55	0.014		0.022	
b1	0.204		0.304	0.008		0.012	
D			10.92			0.430	
E	7.95		9.75	0.313		0.384	
е		2.54			0.100		
e3		7.62			0.300		
e4		7.62			0.300		
F			6.6			0.260	
I			5.08			0.200	
L	3.18		3.81	0.125		0.150	
Z			1.52			0.060	

# OUTLINE AND MECHANICAL DATA





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